# Integrated Circuit Design in Post-moore Era

Guest Editor:

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## Message from the Guest Editor

This Special Issue provides a platform for researchers to report their most recent progress in the field of integrated circuits, including integrated circuit design, technology, packaging and testing, etc. It will bring together, from a global perspective, scientists, researchers, end-users, and industry to exchange ideas, advance knowledge and report key issues of the post-Moore era technology. Topics of interest for this Special Issue include but are not limited to:

- Analog integrated circuit design (including radio frequency circuit)
- System on Chip (SoC)
- Random access memory (RAM)
- Digital circuit design
- IC measurement and test
- IC package
- Key devices in integrated circuits

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Special Issue

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## Message from the Editor-in-Chief

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